Integrated Silicon Pressure Sensor Manifold Absolute Pressure Sensor On-Chip Signal Conditioned, Temperature Compensated and Calibrated

MPX4100 SERIES

INTEGRATED PRESSURE SENSOR 20 TO 105 kPA (2.9 TO 15.2 psi) 0.3 TO 4.9 V OUTPUT

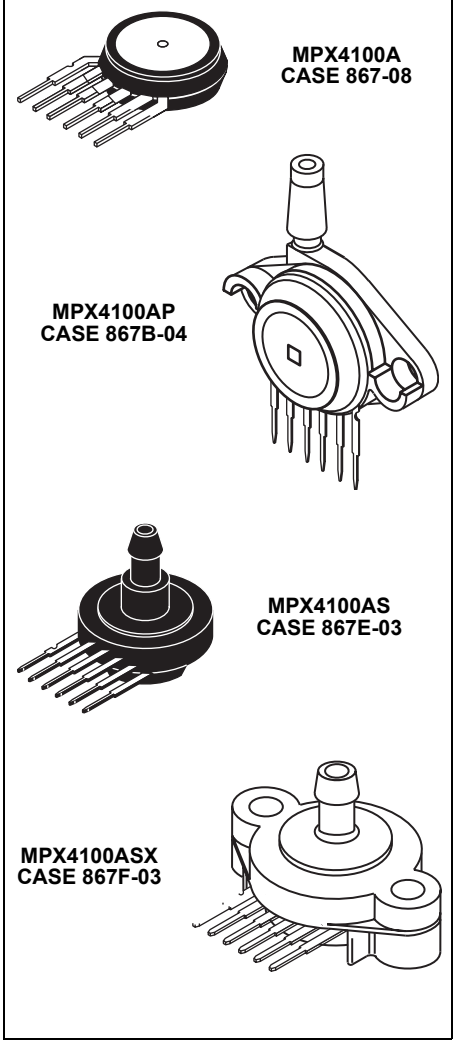
The MPX4100 series Manifold Absolute Pressure (MAP) sensor for engine control is designed to sense absolute air pressure within the intake manifold. This measurement can be used to compute the amount of fuel required for each cylinder. The small form factor and high reliability of on-chip integration makes the MAP sensor a logical and economical choice for automotive system designers.

Features

- 1.8% Maximum Error Over 0° to 85°C
- Specifically Designed for Intake Manifold Absolute Pressure Sensing in Engine Control Systems
- Ideally Suited for Microprocessor Interfacing
- Temperature Compensated Over -40°C to +125°C
- Durable Epoxy Unibody Element
- Ideal for Non-Automotive Applications

Typical Applications

- Manifold Sensing for Automotive Systems



ORDERING INFORMATION[1]				
Device Type	**Options**	**Case No.**	**MPX Series Order Number**	**Device Marking**
Basic Element	Absolute, Element Only	867-08	MPX4100A	MPX4100A
Ported Elements	Absolute, Ported	867B-04	MPX4100AP	MPX4100AP
	Absolute, Stove Pipe Port	867E-03	MPX4100AS	MPX4100A
	Absolute, Axial Port	867F-03	MPX4100ASX	MPX4100A

1. The MPX4100A series MAP silicon pressure sensors are available in the Basic Element, or with pressure port fittings that provide mounting ease and barbed hose connections.

PIN NUMBERS			
1	V_{OUT}	4	NC
2	GND	5	NC
3	V_S	6	NC

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The MPX4100 series piezoresistive transducer is a state-of-the-art, monolithic, signal conditioned, silicon pressure sensor. This sensor combines advanced micromachining techniques, thin film metallization, and bipolar semiconductor processing to provide an accurate, high level analog output signal that is proportional to applied pressure.

Figure 1 shows a block diagram of the internal circuitry integrated on a pressure sensor chip.

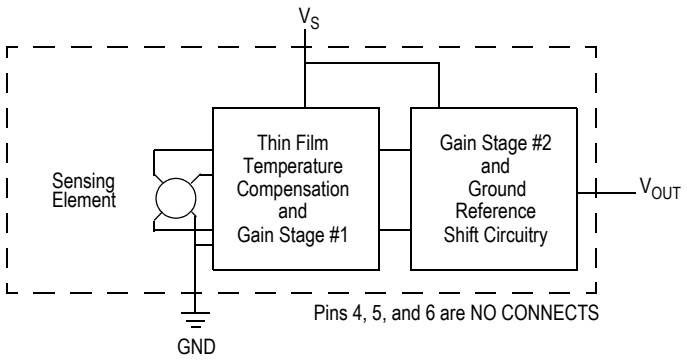


Figure 1. Fully Integrated Pressure Sensor Schematic

Table 1. MAXIMUM RATINGS(1)

Rating	Symbol	Value	Unit
Overpressure(2) (P1 > P2)	P_{max}	400	kPa
Burst Pressure(2) (P1 > P2)	P_{burst}	1000	kPa
Storage Temperature	T_{stg}	-40 to +125	°C
Operating Temperature	T_A	-40 to +125	°C

1. T_C = 25°C unless otherwise noted.
2. Exposure beyond the specified limits may cause permanent damage or degradation to the device.

Table 2. OPERATING CHARACTERISTICS (VS = 5.1 Vdc, TA = 25×C unless otherwise noted, P1 > P2)

Characteristic		Symbol	Min	Typ	Max	Unit
Pressure Range[2]		P_{OP}	20	—	105	kPa
Supply Voltage[2]		V_S	4.85	5.1	5.35	Vdc
Supply Current		I_O	—	7.0	10	mAdc
Minimum Pressure Offset[3] @ V_S = 5.1 V	(0 to 85°C)	V_{off}	0.225	0.306	0.388	Vdc
Full Scale Output[4] @ V_S = 5.1 V	(0 to 85°C)	V_{FSO}	4.815	4.897	4.978	Vdc
Full Scale Span[5] @ V_S = 5.1 V	(0 to 85°C)	V_{FSS}	—	4.59	—	Vdc
Accuracy[6]	(0 to 85°C)	—	—	—	±1.8	$\%V_{FSS}$
Sensitivity		V/P	—	54	—	mV/kPa
Response Time[7]		t_R	—	1.0	—	ms
Output Source Current at Full Scale Output		I_{O+}	—	0.1	—	mAdc
Warm-Up Time[8]		—	—	20	—	ms
Offset Stability[9]		—	—	±0.5	—	$\%V_{FSS}$

1. Decoupling circuit shown in Figure 3 required to meet electrical specifications.
2. 1.0 kPa (kiloPascal) equals 0.145 psi.
3. Offset (V_{off}) is defined as the output voltage at the minimum rated pressure.
4. Full Scale Output (V_{FSO}) is defined as the output voltage at the maximum or full rated pressure.
5. Full Scale Span (V_{FSS}) is defined as the algebraic difference between the output voltage at full rated pressure and the output voltage at the minimum rated pressure.
6. Accuracy (error budget) consists of the following:
   - Linearity: Output deviation from a straight line relationship with pressure over the specified pressure range.
   - Temperature Hysteresis: Output deviation at any temperature within the operating temperature range, after the temperature is cycled to and from the minimum or maximum operating temperature points, with zero differential pressure applied.
   - Pressure Hysteresis: Output deviation at any pressure within the specified range, when this pressure is cycled to and from the minimum or maximum rated pressure, at 25°C.
   - TcSpan: Output deviation over the temperature range of 0 to 85°C, relative to 25°C.
   - TcOffset: Output deviation with minimum rated pressure applied, over the temperature range of 0 to 85°C, relative to 25°C.
   - Variation from Nominal: The variation from nominal values, for Offset or Full Scale Span, as a percent of V_{FSS}, at 25°C.
7. Response Time is defined as the time for the incremental change in the output to go from 10% to 90% of its final value when subjected to a specified step change in pressure.
8. Warm-up is defined as the time required for the product to meet the specified output voltage after the Pressure has been stabilized.
9. Offset stability is the product's output deviation when subjected to 1000 hours of Pulsed Pressure, Temperature Cycling with Bias Test.
10. Device is ratiometric within this specified excitation range.

Table 3. MECHANICAL CHARACTERISTICS

Characteristic	Symbol	Min	Typ	Max	Unit
Weight, Basic Element (Case 867)	—	—	4.0	—	Grams
Common Mode Line Pressure[1]	—	—	—	690	kPa

1. Common mode pressures beyond specified may result in leakage at the case-to-lead interface.

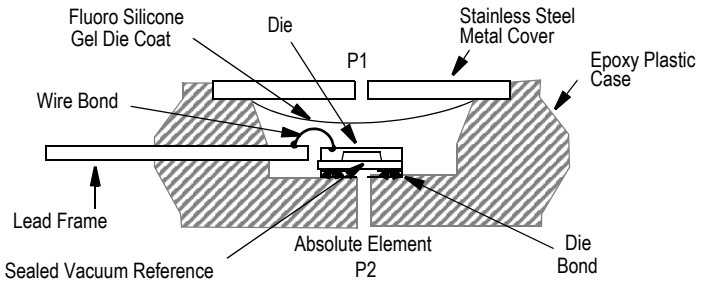


Figure 2. Cross-Sectional Diagram (Not to Scale)

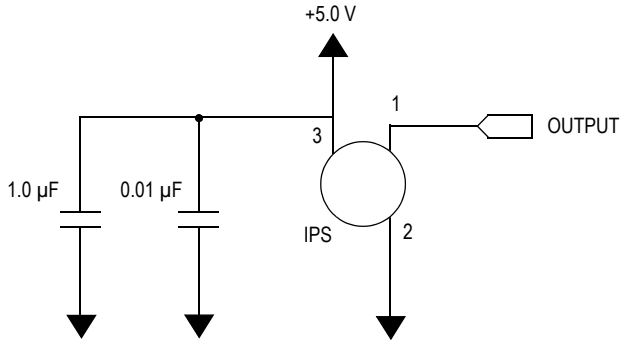


Figure 3. Recommended Power Supply Decoupling
(For output filtering recommendations, refer to Application Note AN1646.)

Figure 2 illustrates an absolute sensing chip in the basic chip carrier (Case 867). A fluorosilicone gel isolates the die surface and wire bonds from the environment, while allowing the pressure signal to be transmitted to the sensor diaphragm. The MPX4100A series pressure sensor operating characteristics, and internal reliability and qualification tests are based on use of dry air as the pressure media. Media, other than dry air, may have adverse effects on sensor performance and long-term reliability. Contact the factory for information regarding media compatibility in your application.

Figure 4 shows the sensor output signal relative to pressure input. Typical, minimum, and maximum output curves are shown for operation over a temperature range of 0° to 85°C. (The output will saturate outside of the specified pressure range.)

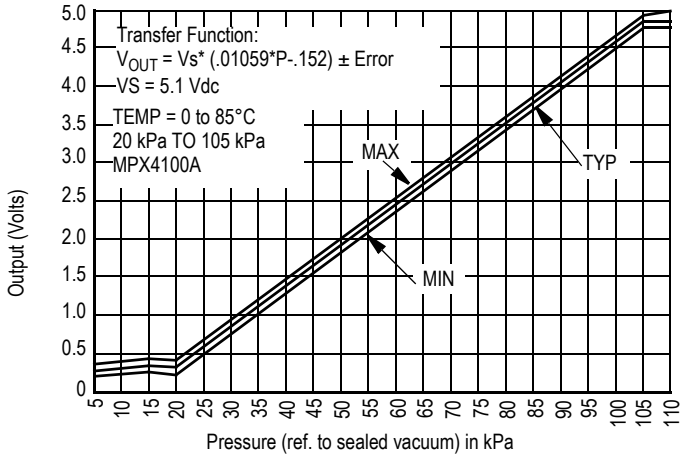


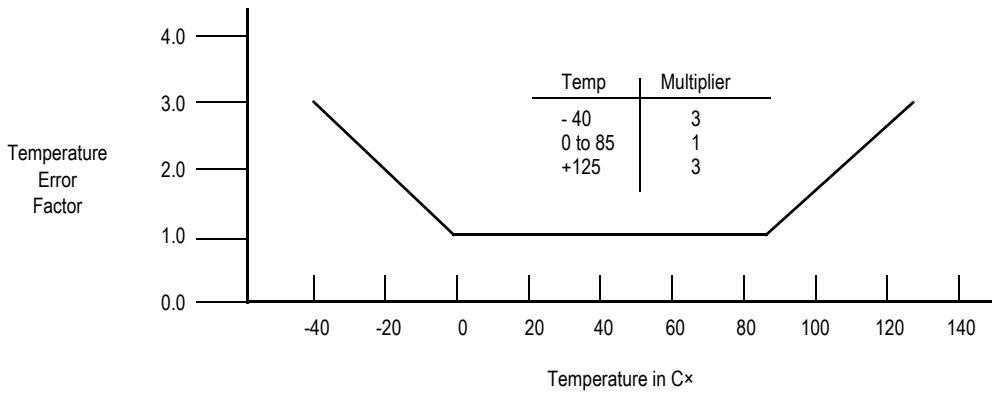
Figure 4. Output versus Absolute Pressure

Transfer Function (MPX4100A)

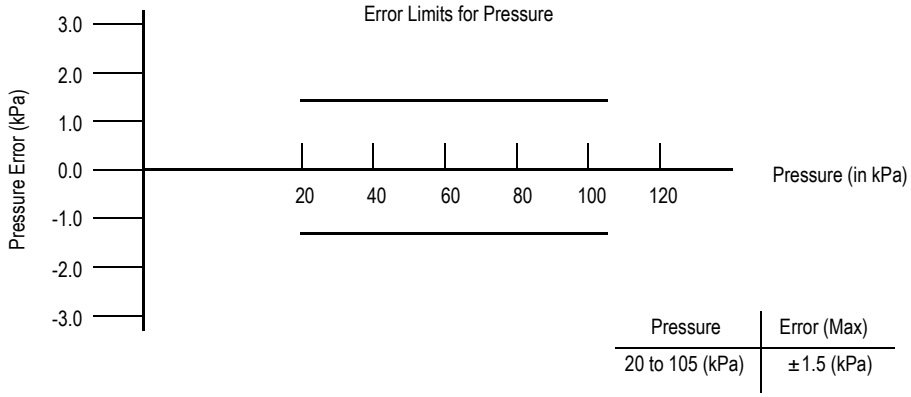
Nominal Transfer Value: $V_{out} = V_S (P \times 0.01059 - 0.1518)$
$\pm$ (Pressure Error x Temp. Factor x 0.01059 x V_S)
$V_S = 5.1 \text{ V} \pm 0.25 \text{ Vdc}$

Temperature Error Band

MPX4100A Series



Pressure Error Band



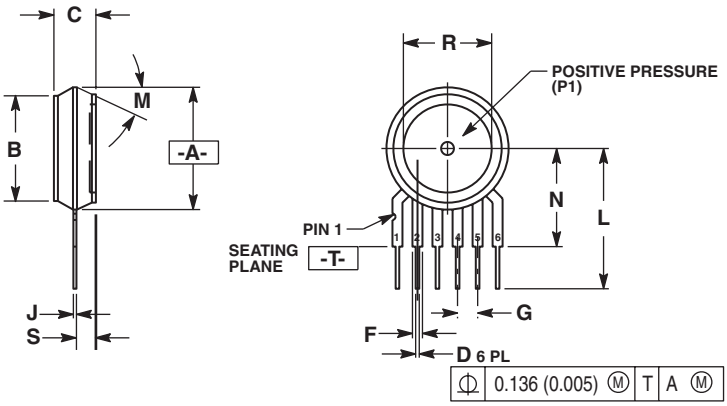
PRESSURE (P1)/VACUUM (P2) SIDE IDENTIFICATION TABLE

The two sides of the pressure sensor are designated as the Pressure (P1) side and the Vacuum (P2) side. The Pressure (P1) side is the side containing fluorosilicone gel, which protects the die from harsh media. The MPX pressure sensor is designed to operate with positive differential pressure applied, P1 > P2.

The Pressure (P1) side may be identified by using the table below:

Part Number	Case Type	Pressure (P1) Side Identifier
MPX4100A	867	Stainless Steel Cap
MPX4100AP	867B	Side with Port Marking
MPX4100AS	867E	Side with Port Attached
MPX4100ASX	867F	Side with Port Attached

PACKAGE DIMENSIONS



NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION -A- IS INCLUSIVE OF THE MOLD STOP RING. MOLD STOP RING NOT TO EXCEED 16.00 (0.630).

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
A	0.595	0.630	15.11	16.00
B	0.514	0.534	13.06	13.56
C	0.200	0.220	5.08	5.59
D	0.027	0.033	0.68	0.84
F	0.048	0.064	1.22	1.63
G	0.100 BSC		2.54 BSC	
J	0.014	0.016	0.36	0.40
L	0.695	0.725	17.65	18.42
M	30° NOM		30° NOM	
N	0.475	0.495	12.07	12.57
R	0.430	0.450	10.92	11.43
S	0.090	0.105	2.29	2.66

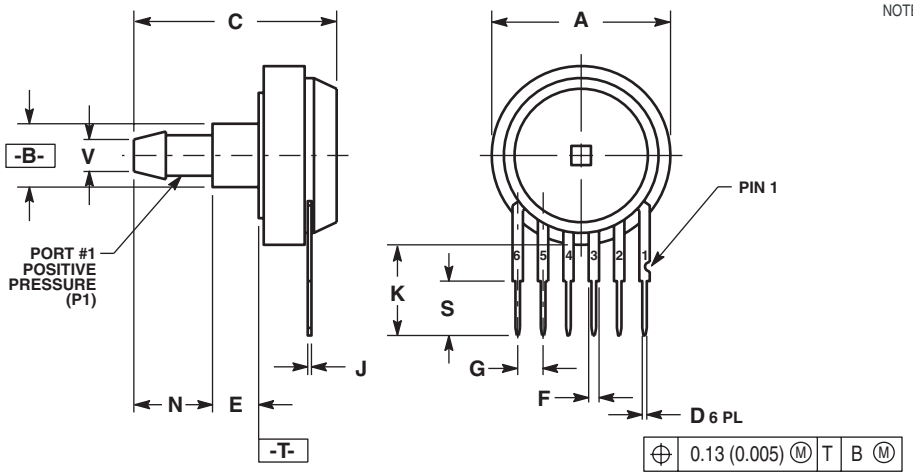
STYLE 1:
PIN 1. VOUT
2. GROUND
3. VCC
4. V1
5. V2
6. VEX

STYLE 2:
PIN 1. OPEN
2. GROUND
3. -VOUT
4. VSUPPLY
5. +VOUT
6. OPEN

STYLE 3:
PIN 1. OPEN
2. GROUND
3. +VOUT
4. +VSUPPLY
5. -VOUT
6. OPEN

CASE 867-O8
ISSUE N
BASIC ELEMENT

PACKAGE DIMENSIONS

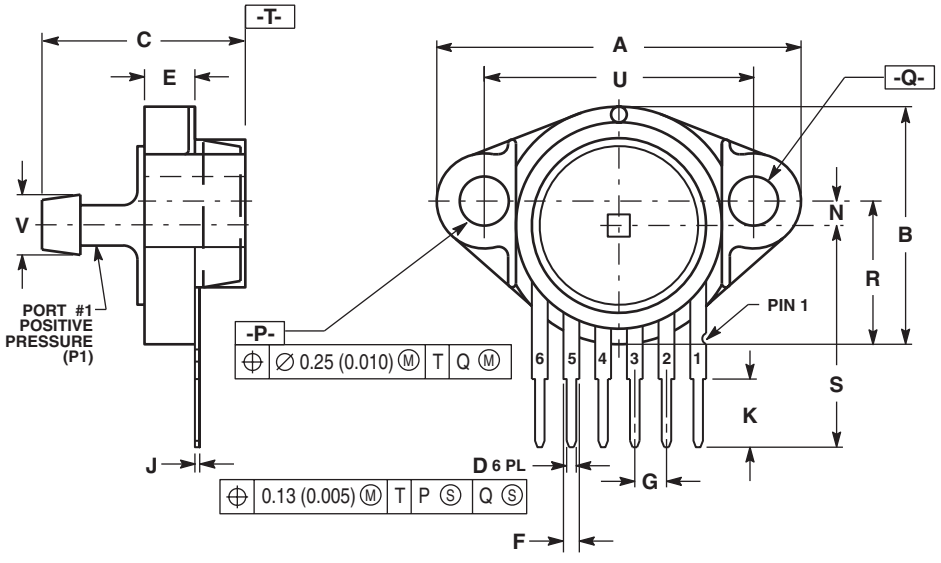


NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
A	0.690	0.720	17.53	18.28
B	0.245	0.255	6.22	6.48
C	0.780	0.820	19.81	20.82
D	0.027	0.033	0.69	0.84
E	0.178	0.186	4.52	4.72
F	0.048	0.064	1.22	1.63
G	0.100 BSC		2.54 BSC	
J	0.014	0.016	0.36	0.41
K	0.345	0.375	8.76	9.53
N	0.300	0.310	7.62	7.87
S	0.220	0.240	5.59	6.10
V	0.182	0.194	4.62	4.93

STYLE 1:
PIN 1. V_{OUT}
2. GROUND
3. V_{CC}
4. V1
5. V2
6. V_{EX}

CASE 867E-O3
ISSUE D
STOVE PIPE PORT (AS)



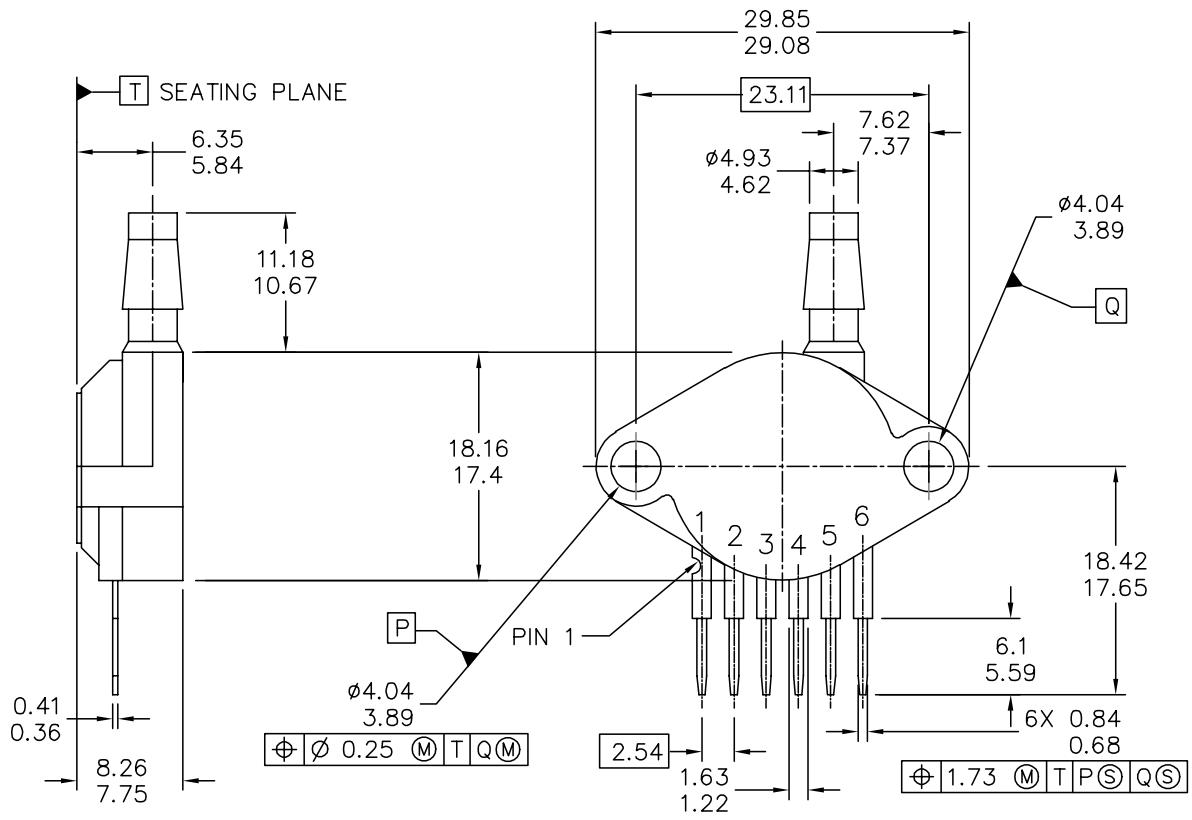
NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
A	1.080	1.120	27.43	28.45
B	0.740	0.760	18.80	19.30
C	0.630	0.650	16.00	16.51
D	0.027	0.033	0.68	0.84
E	0.160	0.180	4.06	4.57
F	0.048	0.064	1.22	1.63
G	0.100 BSC		2.54 BSC	
J	0.014	0.016	0.36	0.41
K	0.220	0.240	5.59	6.10
N	0.070	0.080	1.78	2.03
P	0.150	0.160	3.81	4.06
Q	0.150	0.160	3.81	4.06
R	0.440	0.460	11.18	11.68
S	0.695	0.725	17.65	18.42
U	0.840	0.860	21.34	21.84
V	0.182	0.194	4.62	4.93

STYLE 1:
PIN 1. V_{OUT}
2. GROUND
3. V_{CC}
4. V1
5. V2
6. V_{EX}

CASE 867F-03
ISSUE D
AXIAL PORT (ASX)

PACKAGE DIMENSIONS



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	CASE NUMBER: 867B-04	28 JUL 2005
	STANDARD: NON-JEDEC	

CASE 867B-04
ISSUE G
PORTED (AP)

PACKAGE DIMENSIONS

NOTES:

1. DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONS AND TOLERANCES PER ASME Y14.5M–1994.
3. 867B–01 THRU –3 OBSOLETE, NEW STANDARD 867B–04.

STYLE 1:

PIN 1: V OUT
2: GROUND
3: VCC
4: V1
5: V2
6: V EX

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	STANDARD: NON–JEDEC	

CASE 867B-04
ISSUE G
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